

Amendments to Claims:

1 (currently amended): An improved process for bonding difficult-to-bond substrates comprising bonding a first substrate to a second substrate with a thermoplastic hot melt adhesive composition, said composition ~~comprising~~ consisting of an ethylene n-butyl acrylate copolymer, a wax, and a modified terpene tackifier and, optionally, an additional ethylene copolymer, an oil and/or an antioxidant.

2 (original): The process of claim 1 wherein the modified terpene is a terpene phenolic.

3 (currently amended): The process of claim 1 ~~further comprising a wax~~ wherein said additional ethylene copolymer is ethylene vinyl acetate.

4 (original): The process of claim 1 wherein the difficult-to-bond substrate is a UV varnish treated substrate or an acrylic varnish treated substrate.

5 (original): The process of claim 4 wherein the substrate to be bonded is made of paper or paperboard.

6 (original): The process of claim 1 wherein the substrate to be bonded is a grease resistance treated substrate.

7 (original): The process of claim 6 wherein the substrate to be bonded is a fluorochemical treated substrate.

8 (original): The process of claim 7 wherein the substrate is made of paper or paperboard.

9-20 (canceled)

21 (currently amended): The process ~~An improved process for bonding difficult to bond substrates comprising bonding a first substrate to a second substrate with a hot melt adhesive composition, of claim 1 wherein said composition consisting essentially consists~~ of 30 to 45 % by weight ethylene n-butyl acrylate copolymer, 30 to 55 % by weight of a modified terpene tackifier, and 20 10 to 40 % by weight wax, ~~wherein the tackifier comprises at least one modified terpene tackifier up to 25 % by weight of an ethylene vinyl acetate copolymer and up to 3 % by weight of an antioxidant.~~

22 (previously presented): The process of claim 21 wherein the modified terpene is a terpene phenolic.

23 (previously presented): The process of claim 21 wherein the difficult-to-bond substrate is a UV varnish treated substrate or an acrylic varnish treated substrate.

24 (previously presented): The process of claim 23 wherein the substrate to be bonded is made of paper or paperboard.

25 (previously presented): The process of claim 21 wherein the substrate to be bonded is a grease resistance treated substrate.

26 (previously presented): The process of claim 25 wherein the substrate to be bonded is a fluorochemical treated substrate.

27 (previously presented): The process of claim 26 wherein the substrate is made of paper or paperboard.

28 (previously presented): The process of claim 21 wherein said first and/or said second substrate has a surface energy of from about 35dyn/cm down to about 25dyn/cm.

29 (previously presented): The process of claim 1 wherein said first and/or said second substrate has a surface energy of from about 35dyn/cm down to about 25dyn/cm.

30 (currently amended): An improved process for bonding difficult-to-bond substrates comprising bonding a first substrate to a second substrate with a hot melt adhesive composition, said composition consisting essentially of an ethylene copolymer component, a tackifier

component, a ~~and~~ wax component and an antioxidant, wherein said ethylene copolymer comprises an ethylene n-butyl acrylate copolymer and said tackifier component comprises a modified terpene tackifier.

31 (previously presented): The process of claim 30 wherein the modified terpene is a terpene phenolic.

32 (previously presented): The process of claim 30 wherein the difficult-to-bond substrate is a UV varnish treated substrate, an acrylic varnish treated substrate or a fluorochemical treated substrate.